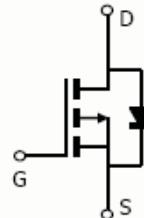


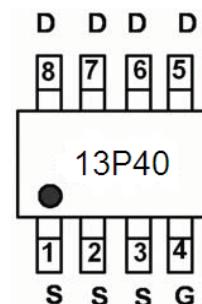
## P-Channel Enhancement Mode Power MOSFET



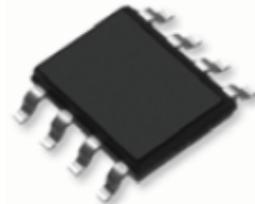
### Description

The RM13P40S8 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

Schematic diagram



Marking and pin assignment



SOP-8 top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
13P40	RM13P40S8	SOP-8	Ø330mm	12mm	2500 units

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-13	A
Drain Current-Continuous( $T_c=100^\circ\text{C}$ )	$I_D (100^\circ\text{C})$	-9	A
Pulsed Drain Current	$I_{DM}$	50	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance ,Junction-to-Ambient(Note 2)	$R_{\theta JA}$	50	°C/W
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## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

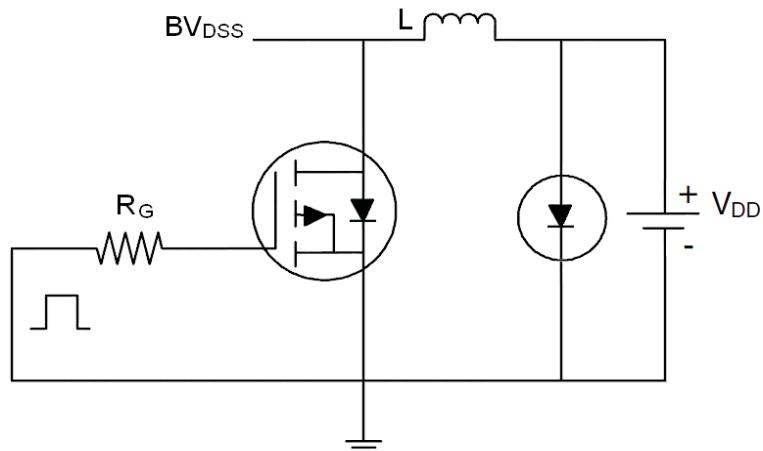
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-40	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.3	-2	-2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-12\text{A}$	-	12	15	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-10\text{A}$	35	-	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2800	-	PF
Output Capacitance	$C_{\text{oss}}$		-	320	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	220	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-20\text{V}, R_{\text{L}}=2\Omega$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=6\Omega$	-	11	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	75	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	89	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	35	-	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=-20\text{V}, I_{\text{D}}=-12\text{A}, V_{\text{GS}}=-10\text{V}$	-	40	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	6	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	12	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-12\text{A}$	-	-	1.2	V
Diode Forward Current (Note 2)	$I_{\text{S}}$		-	-	-13	A

### Notes:

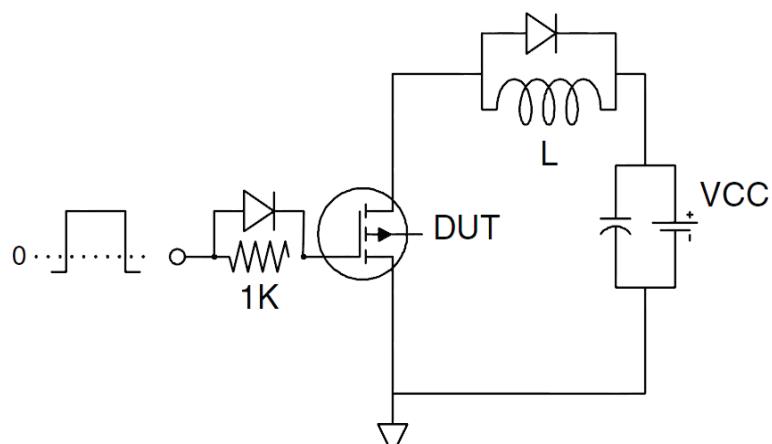
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

## Test Circuit

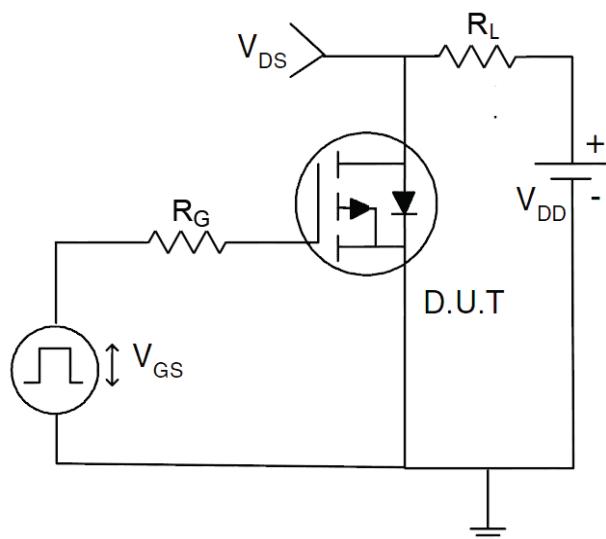
### 1) E<sub>AS</sub> Test Circuit



### 2) Gate Charge Test Circuit



### 3) Switch Time Test Circuit



## RATING AND CHARACTERISTICS CURVES (RM13P40S8)

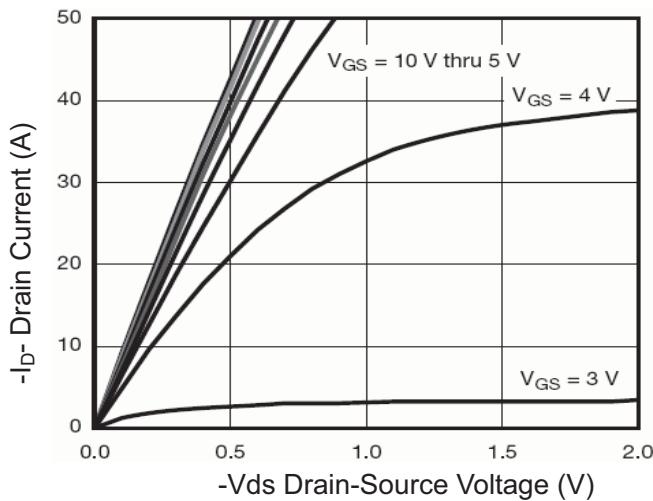


Figure 1 Output Characteristics

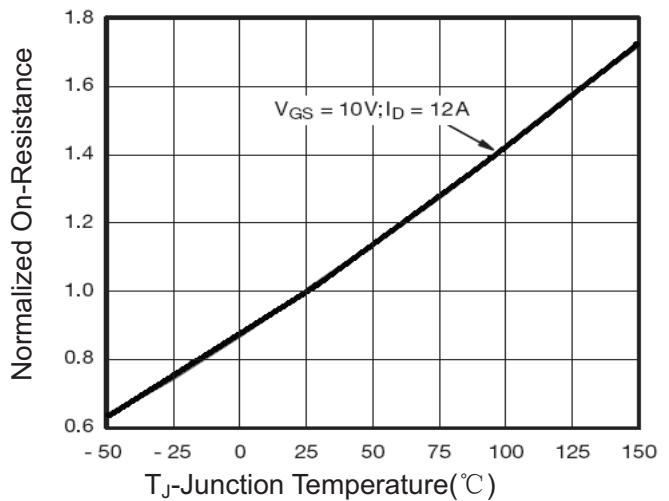


Figure 4 Rdson-Junction Temperature

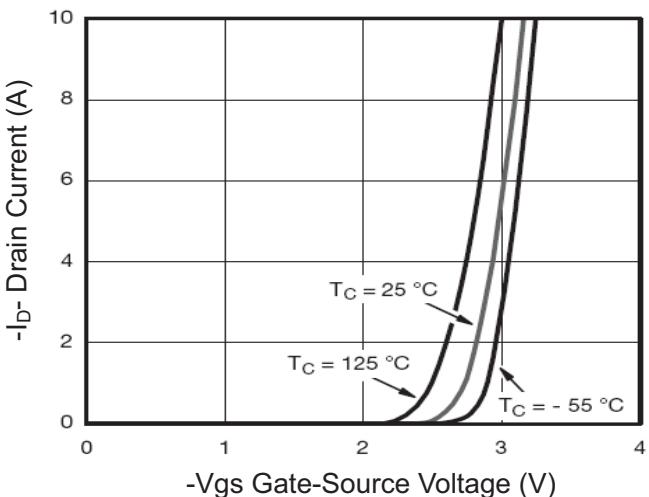


Figure 2 Transfer Characteristics

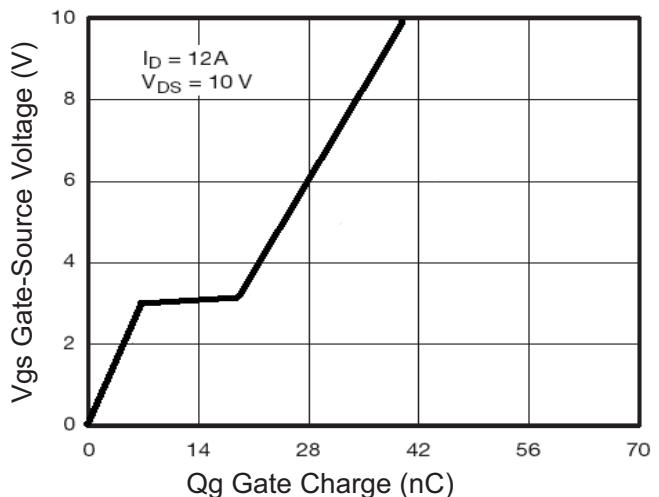


Figure 5 Gate Charge

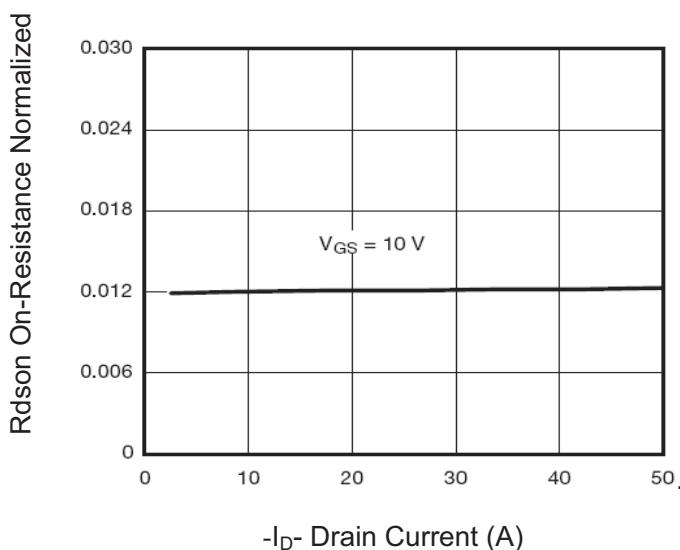


Figure 3 Rdson-Drain Current

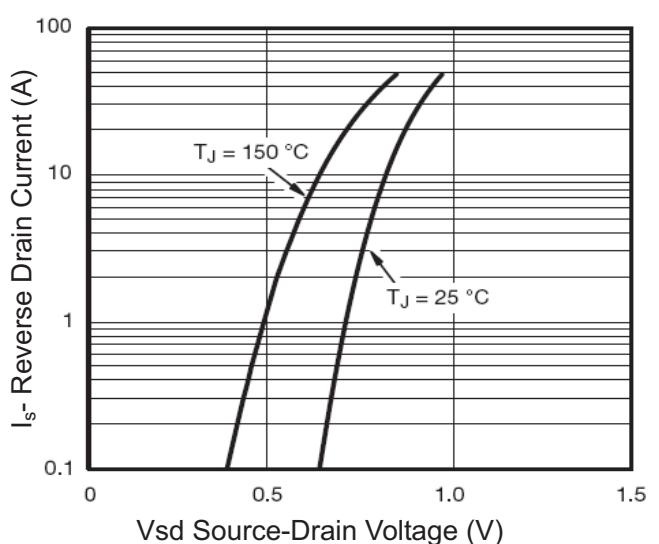


Figure 6 Source-Drain Diode Forward

## RATING AND CHARACTERISTICS CURVES (RM13P40S8)

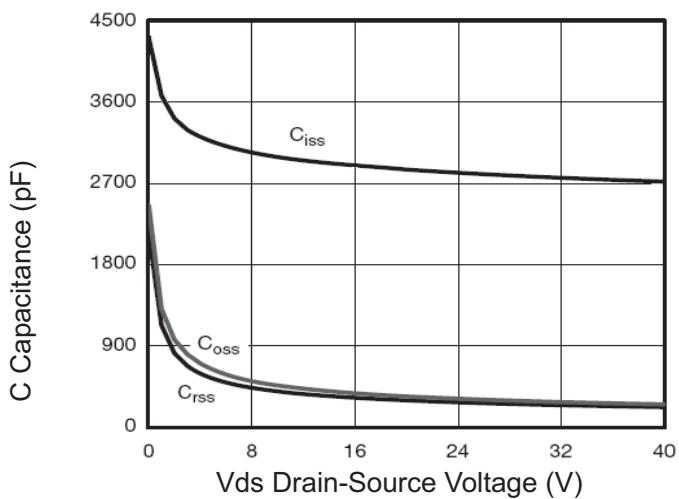


Figure 7 Capacitance vs Vds

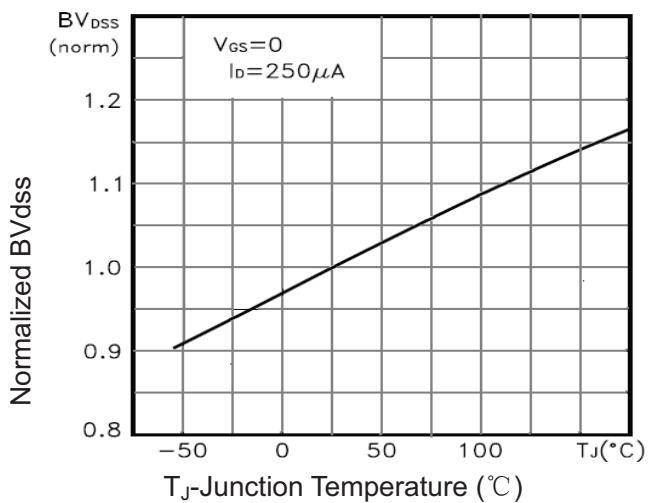


Figure 9  $BV_{dss}$  vs Junction Temperature

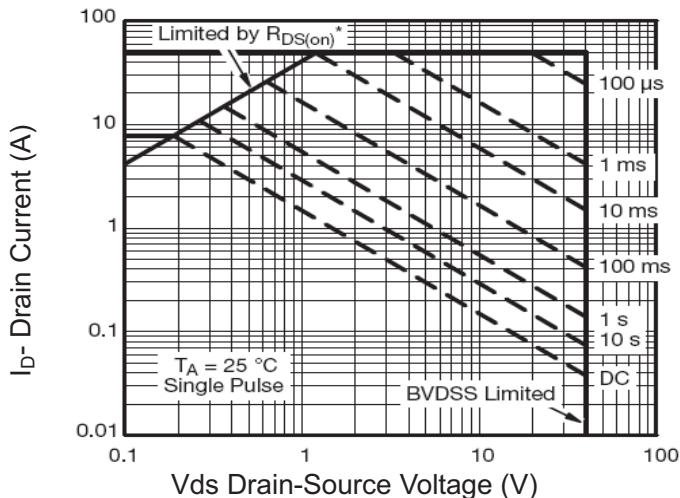


Figure 8 Safe Operation Area

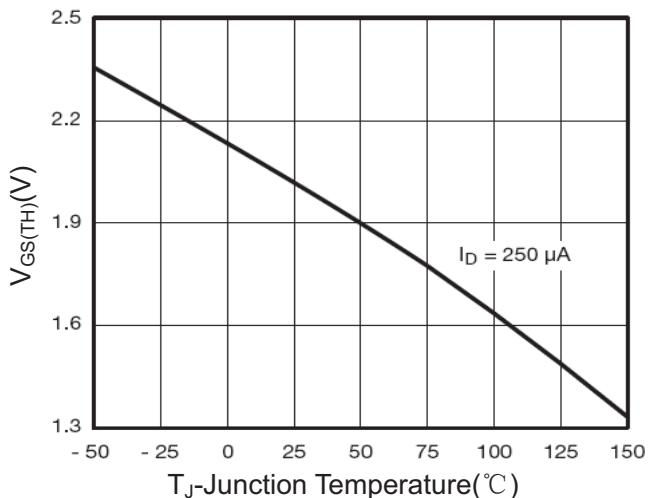


Figure 10  $V_{GS(th)}$  vs Junction Temperature

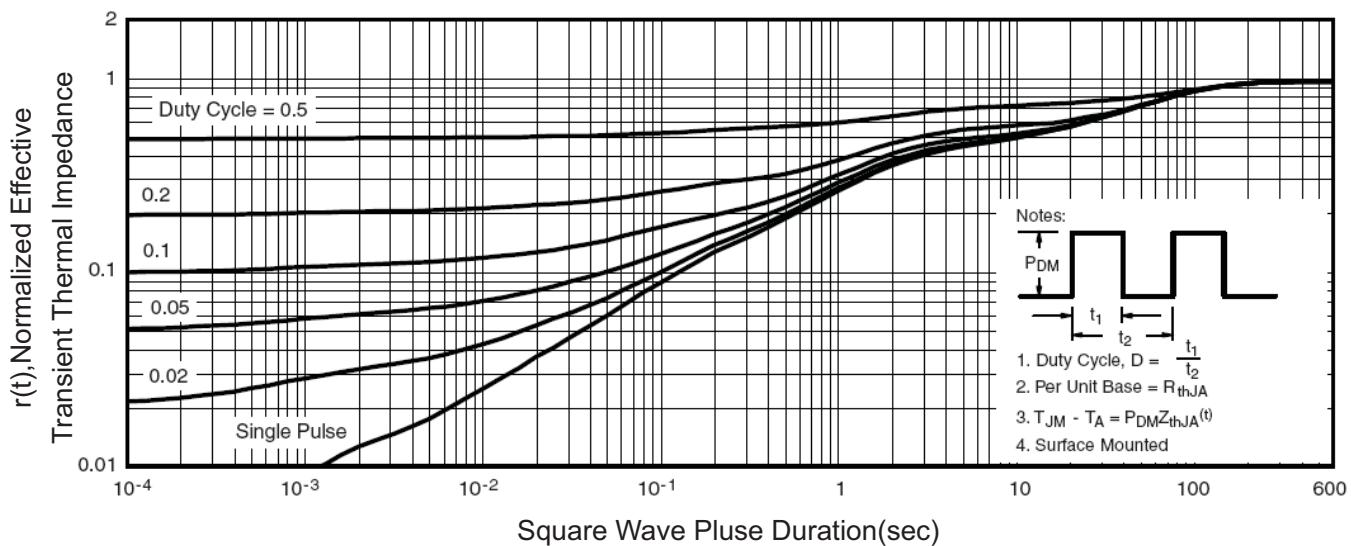
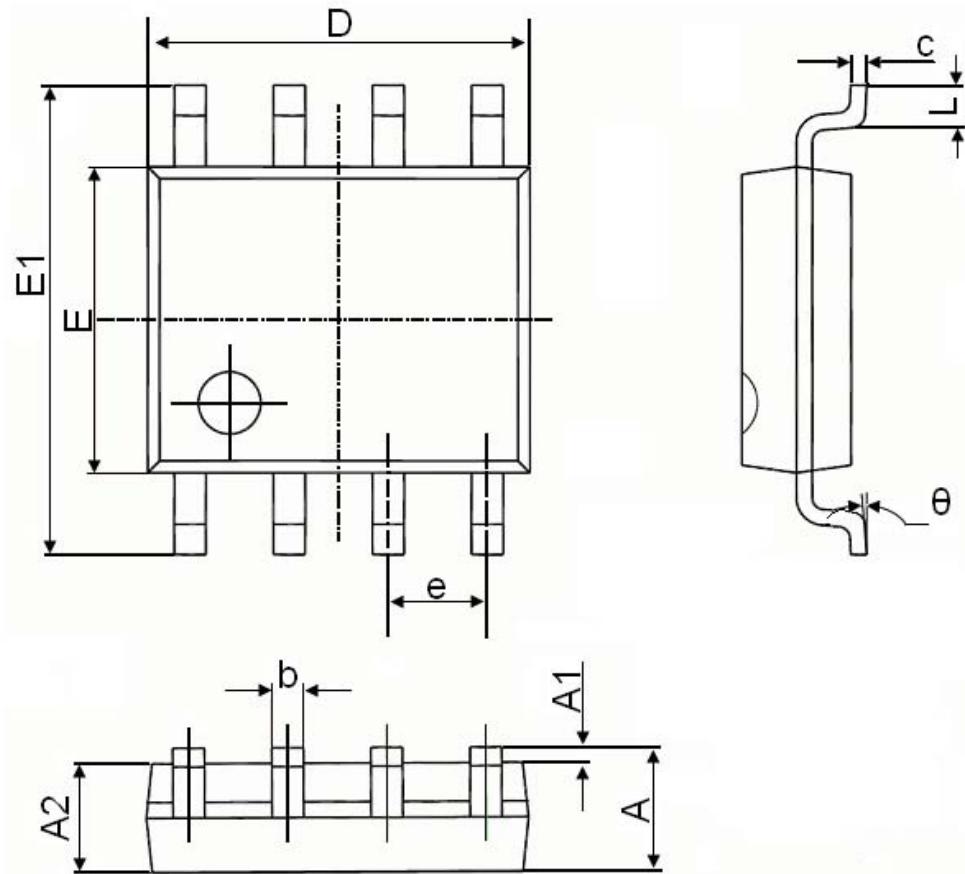


Figure 11 Normalized Maximum Transient Thermal Impedance

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°		8°	